

Figure 4. FETRON Production. Methods used for assembly are the best industry quality control standards, MIL-STD-883. Assembly procedures are carefully planned and carried out under ultra-clean conditions to maximize FETRON reliability.

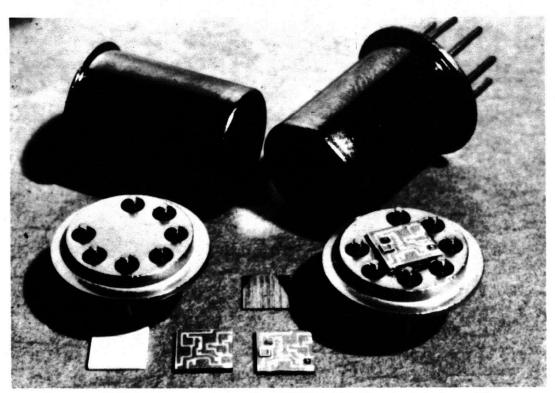


Figure 5. FETRON Assembly Steps. The FETRON thick film circuit is shown (1) as a clean substrate, (2) with conductive film, (3) with circuit etched, and (4) with circuit chips attached. The completed circuit is then soldered to the header and connected to the posts with gold wires. The header is then hermetically sealed with a nickel-plated cap.